



801 N 10/023,819

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Biju Chandran et al. Examiner: John Vigushin
Serial No.: 10/023,819 Group Art Unit: 2827
Filed: December 21, 2001 Docket: 884.A27US1
Title: CHIP JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN
THE ADHERENTS AND SEMICONDUCTOR PACKAGE MADE THEREBY

Assignee: Intel Corporation

Customer No: 21186

AMENDMENT UNDER 37 C.F.R. § 1.312(a)

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Notice of Allowance mailed April 25, 2005, please amend the above-identified application as follows: